Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **1A**
2. **1N.Y**
3. **2A**
4. **2N.Y**
5. **3A**
6. **3N.Y**
7. **GND**
8. **4N.Y**
9. **4A**
10. **5N.Y**
11. **5A**
12. **6N.Y**
13. **6A**
14. **VCC**

**2 1 14 13**

**6 7 8 9**

**3**

**4**

**5**

**12**

**11**

**10**

**MASK**

**REF**

**HCT04E**

**Top Material: Al**

**Backside Material: Si Ni**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Vcc**

**Mask Ref: HCT04E**

**APPROVED BY: DK DIE SIZE .052” X .054” DATE: 5/1/23**

**MFG: TEXAS INSTRUMENTS THICKNESS .025” P/N: 54HCT04**

**DG 10.1.2**

#### Rev B, 7/19/02